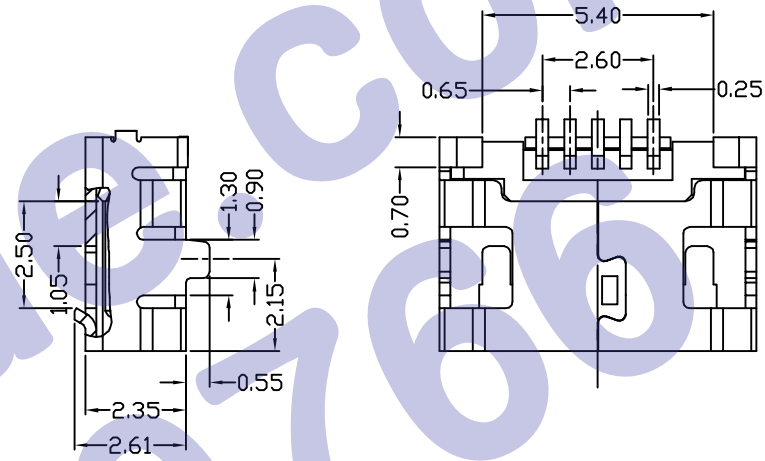
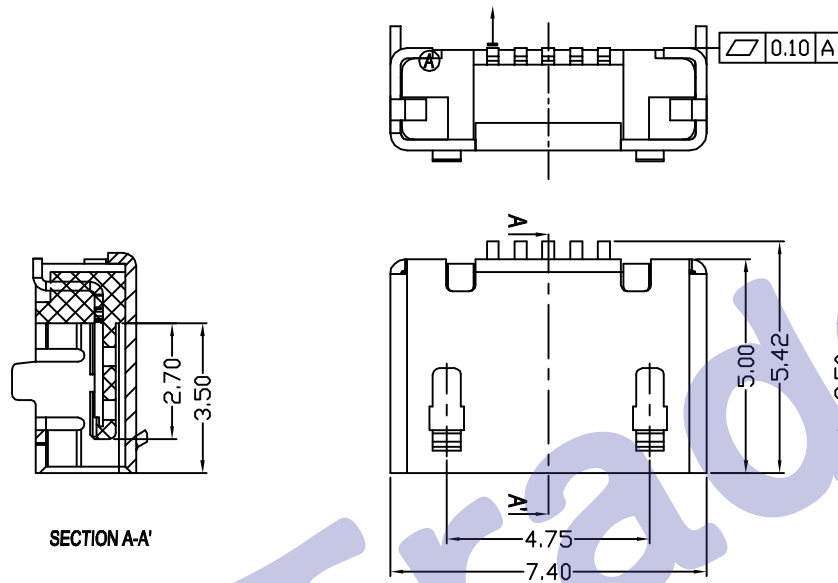
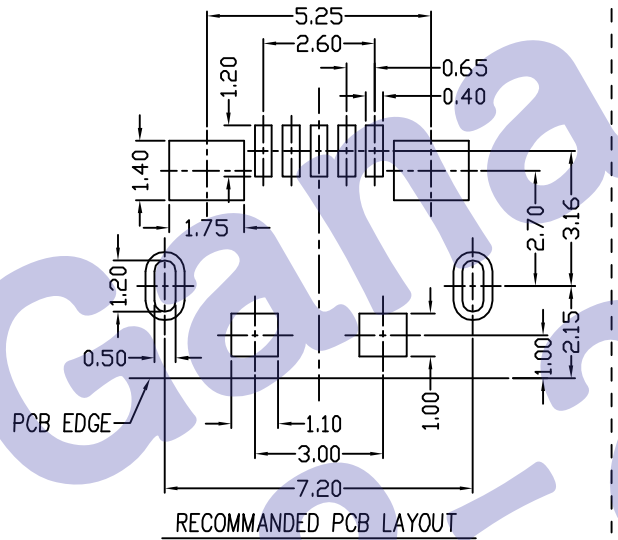
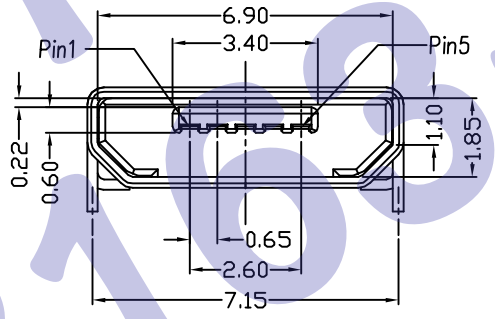


REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE	REVSER	APPD



Notes:

1. Materials:
 - 1.1 Housing: High temperature thermoplastic with g.f,UL94 v-0.
 - 1.2 Contact: copper alloy,t=0.20mm.
 - 1.3 Shell: copper alloy,t=0.25mm.
2. Specifications:
 - 2.1. Current rating: 1 A Max.
 - 2.2. Dielectric withstanding:voltage: 100 V(ac) for 1 min.
 - 2.3. Contact resistance: 50 mW Max.
 - 2.4. Insulation resistance: 100 MW Min.
 - 2.5. Total mating force: 3.57 Kgf Max.
 - 2.6. Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
 - 2.7. Temperature range: -30°C~+80°C



No.	Name	Q'ty	Finish
3	Shell	1	N/A
2	Contact	5	N/A
1	Housing	1	N/A

PART NO: 1-MD05SMXXX-01	MATERIAL: SEE NOTE
MODEL NO:	FINSH: SEE NOTE
UNIT: mm	SIZE: A4
TOLERANCE UNSPECIFIED	
.x	±0.38
.xx	±0.25
.xxx	±0.13
ANG.	±2°
COLOR: SEE NOTE	DR: ???
CHK:	APP:

HDC有限公司

TITLE: Micro usb 5P/F B Type SMT
(外壳DIP 7.2)

DWG NO: MU092	REV: A
SCALE: 1:1	SHEET: 1/1